L Number		Search Text	DB	Time stamp
-	144	system and substrate and ((polymer resin) and (magnetic	USPAT,	2004/05/28 09:56
		ferro\$2magnetic titanate barium adj strontium adj titanate	US-PGPUB	
		strontium adj tantalum adj oxide perovskite)) same		
		(interconnect\$4 coupling adj component packaging) and		
		(print\$6 adj circuit adj board 'PCB' aluminum near2 frame grid near2 array)		
	2	(system and substrate and ((polymer resin) and (magnetic	USPAT:	2004/05/28 09:56
-	- 2	ferroS2magnetic titanate barium adj strontium adj titanate	US-PGPUB	2004/05/28 09:56
		strontium adj tentalum adj oxide perovskite)) same	US-FGFUB	
		(interconnect\$4 coupling adj component packaging) and		
		(print\$6 adj circuit adj board "PCB" aluminum near2 frame		
		grid near2 array)) and screen adi pad\$2		
.	4	screen adj pad and (printed adj circuit adj board 'PCB' grid	USPAT:	2004/05/28 09:57
		near5 array aluminum near2 frame) and (interconnect	US-PGPUB	
		packaging magnetically near5 align\$3)		
-	18	system and substrate and ((polymer resin) and (magnetic	USPAT;	2004/05/28 09:58
		ferro\$2magnetic titanate barium adj strontium adj titanate	US-PGPUB	
		strontium adj tantalum adj oxide perovskite)) same		
		(interconnect\$4 coupling adj component packaging) and		
		(print\$6 adj circuit adj board PCB aluminum near2 frame	1	J.
		grid near2 array) and magnet\$\$7 near5 align\$3 and conductive near5 interconnect		1
- '	37	(system and substrate and ((polymer resin) and (magnetic	USPAT:	2004/05/28 09:59
	37	ferro\$2magnetic titanate barium adj strontium adj titanate	US-PGPUB	2004/05/28 09:59
		strontium adj tantalum adj oxide perovskite)) same	US-PGPUB	
		(interconnect\$4 coupling adj component packaging) and		
		(print\$6 adj circuit adj board PCB' aluminum near2 frame		
		grid near2 array)) and (particle grain) near2 (size nano	1	
		nanosize micron ultra\$2fine) and (acrcular near5 shape	1	
		(length width aspect diameter) near2 ratio)		
-	31	(system and substrate and ((polymer resin) and (magnetic	USPAT;	2004/05/28 10.00
		ferro\$2magnetic titanate barium adj strontium adj titanate	US-PGPUB	
		strontium adj tantalum adj oxide perovskite)) same		
		(interconnect\$4 coupling adj component packaging) and	l	
		(print\$8 adj circuit adj board PCB' aluminum near2 frame grid near2 array)) and (weight wt) near2 (ratio part %6)	1	1
•	19	(system and substrate and ((polymer resin) and (magnetic	USPAT:	2004/05/28 10:00
		ferro\$2magnetic titanate barium adi strontium adi titanate	US-PGPUR	2004/05/26 10:00
		strontium adj tantalum adj oxido perovskite)) same	USFGFUB	
		(interconnect\$4 coupling adj component packaging) and		
		(print\$6 adj circuit adj board 'PCB' aluminum near2 frame		
		grid near2 array)) and (photo\$2resist) and (thermal adi		
		expansion)		
-	24	((polymer thermoplastic thermoset photo\$2resist DNQ\$4	USPAT;	2004/05/28 10:00
1		diazonaphthoquinone novolac epoxy polyamide) and	US-PGPUB	
		(magnetic ferro\$2magnetic titanate iron magnetite banum		
		adj strontium adj titanate strontium adj tantalum adj oxide		
		perovskite) and (particle powder fiber grain) near5 align\$4 near5 magnetic) and conductive near5 interconnect		
	10	(epoxy polyamide) and (magnetic ferro\$2magnetic titanate	USPAT:	2004/05/28 10:00
	10	iron magnetite barium adi strontium adi titanate strontium adi	US-PGPUB	2004/05/28 10:00
- 1		tantalum adi oxide perovskite) and (particle powder fiber	US-FGFUB	
ĺ		grain) near5 align\$4 near5 magnetic and conductive near5		
		interconnect		
•	18	(((polymer thermoplastic thermoset polyamide epoxy	EPO; JPO;	2004/05/28 10:01
		photo\$2resist DNQ\$4 diazonaphthoquinone novolac) and	DERWENT:	
		(magnetic ferro\$2magnetic titanate iron magnetite	IBM_TDB	
		perovskite)) and (particle powder fiber grain) near5 align\$4)	_	
		and (conductive interconnect\$4 packag\$4)		
	38	"5232661" "5536908" "5526978" "09023049"	USPAT;	2004/05/28 10:01
			US-PGPUB;	
			EPO; JPO;	
			DERWENT	§